MC10161

Binary to 1-8 Decoder (Low)

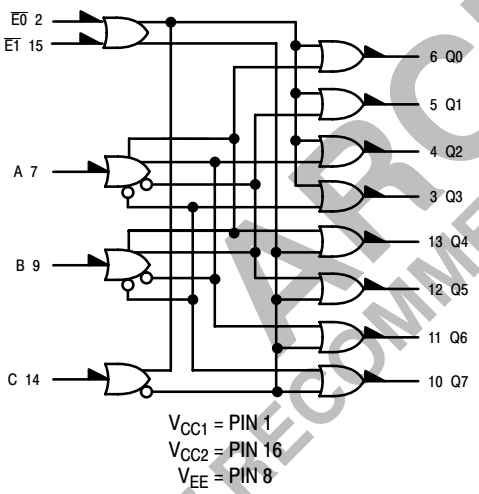
The MC10161 is designed to decode a three bit input word to a one of eight line output. The selected output will be low while all other outputs will be high. The enable inputs, when either or both are high, force all outputs high.

The MC10161 is a true parallel decoder. No series gating is used internally, eliminating unequal delay times found in other decoders. This design provides the identical 4 ns delay from any address or enable input to any output.

A complete mux/demux operation on 16 bits for data distribution is illustrated in Figure 1. This system, using the MC10136 control counters, has the capability of incrementing, decrementing or holding data channels. When both S0 and S1 are low, the index counters reset, thus initializing both the mux and demux units. The four binary outputs of the counter are buffered by the MC10161s to send twisted–pair select data to the multiplexer/demultiplexer to units.

- P_D = 315 mW typ/pkg (No Load)
- t_{pd} = 4.0 ns typ
- t_r, t_f = 2.0 ns typ (20%–80%)

LOGIC DIAGRAM



TRUTH TABLE

ENABLE INPUTS		INPUTS			OUTPUTS							
$\overline{E1}$	$\overline{E0}$	C	B	A	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
L	L	L	L	L	L	H	H	H	H	H	H	H
L	L	L	L	H	H	L	H	H	H	H	H	H
L	L	L	H	L	H	H	L	H	H	H	H	H
L	L	L	H	H	H	H	H	L	H	H	H	H
L	L	H	L	L	H	H	H	H	L	H	H	H
L	L	H	L	H	H	H	H	H	H	L	H	H
L	L	H	H	L	H	H	H	H	H	H	L	H
L	L	H	H	H	H	H	H	H	H	H	H	L
H	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	H	H	H	H	H	H	H	H

ON Semiconductor

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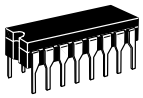
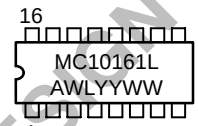
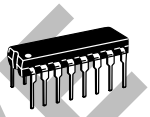
MARKING DIAGRAMS



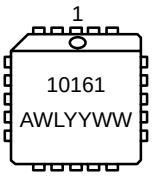
CDIP–16
L SUFFIX
CASE 620





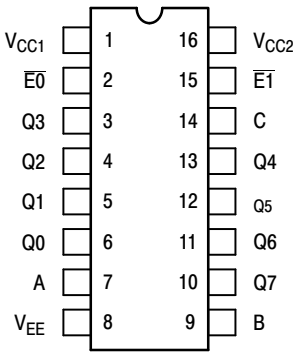
PDIP–16
P SUFFIX
CASE 648

PLCC–20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10161L	CDIP–16	25 Units / Rail
MC10161P	PDIP–16	25 Units / Rail
MC10161FN	PLCC–20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

Characteristic		Symbol	Pin Under Test	Test Limits –30°C Min	Test Limits –30°C Max	Test Limits +25°C Min	Test Limits +25°C Typ	Test Limits +25°C Max	Test Limits +85°C Min	Test Limits +85°C Max	Unit
Power Supply Drain Current		I_E	8		84		61	76		84	mAdc
Input Current		I_{inH}	14		350			220		220	µAdc
		I_{inL}	14	0.5		0.5			0.3		µAdc
Output Voltage	Logic 1	V_{OH}	13 13	–1.060 –1.060	–0.890 –0.890	–0.960 –0.960		–0.810 –0.810	–0.890 –0.890	–0.700 –0.700	Vdc
Output Voltage	Logic 0	V_{OL}	13	–1.890	–1.675	–1.850		–1.650	–1.825	–1.615	Vdc
Threshold Voltage	Logic 1	V_{OHA}	13 13	–1.080 –1.080		–0.980 –0.980			–0.910 –0.910		Vdc
Threshold Voltage	Logic 0	V_{OLA}	13		–1.655			–1.630		–1.595	Vdc
Switching Times (50Ω Load)											ns
Propagation Delay		t_{14+13-} t_{14-13+}	13 13	1.5 1.5	6.2 6.2	1.5 1.5	4.0 4.0	6.0 6.0	1.5 1.5	6.4 6.4	
Rise Time	(20 to 80%)	t_{13+}	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	
Fall Time	(20 to 80%)	t_{13-}	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	

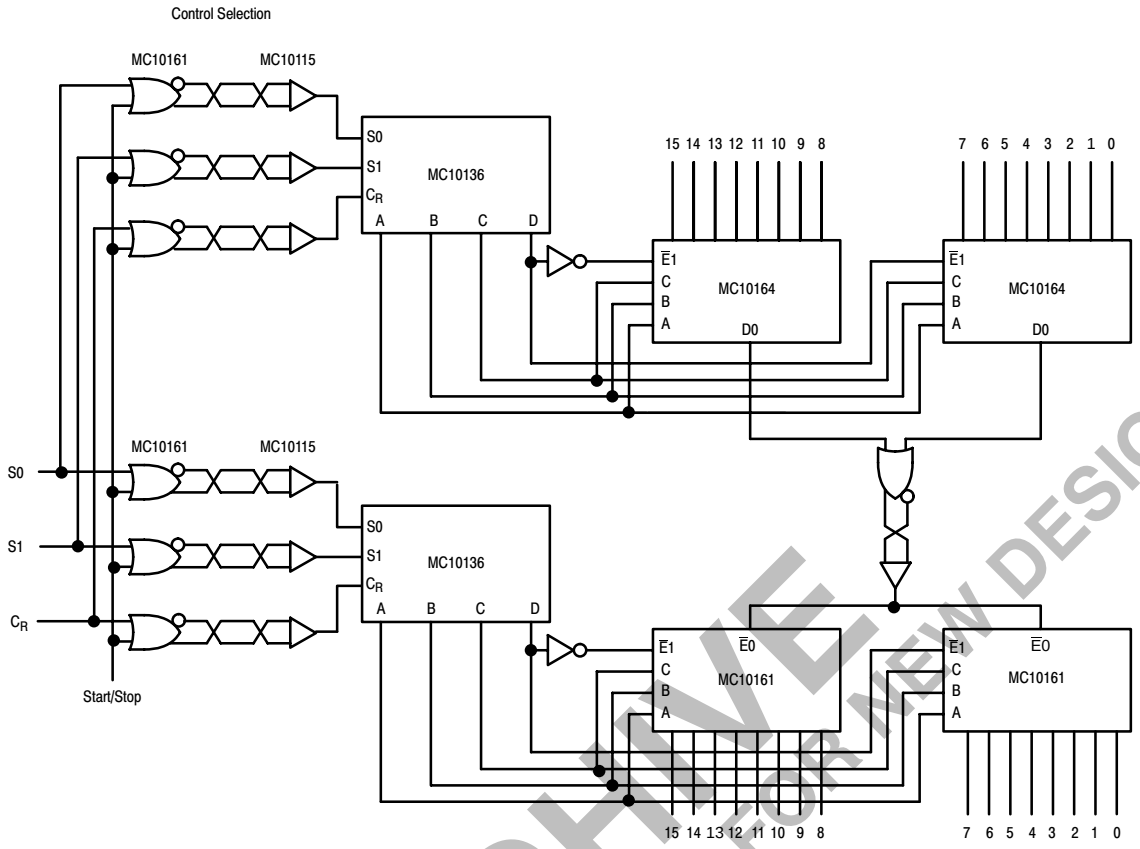
ELECTRICAL CHARACTERISTICS (continued)

@ Test Temperature	V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}
–30°C	–0.890	–1.890	–1.205	–1.500	–5.2
+25°C	–0.810	–1.850	–1.105	–1.475	–5.2
+85°C	–0.700	–1.825	–1.035	–1.440	–5.2

Characteristic		Symbol	Pin Under Test	TEST VOLTAGE APPLIED TO PINS LISTED BELOW V_{IHmax}	V_{ILmin}	V_{IHAmin}	V_{ILAmax}	V_{EE}	(V_{CC}) Gnd
Power Supply Drain Current		I_E	8	2,7,9,14,15				8	1,16
Input Current		I_{inH}	14	14				8	1,16
		I_{inL}	14		14			8	1,16
Output Voltage	Logic 1	V_{OH}	13 13	2 15				8 8	1,16 1,16
Output Voltage	Logic 0	V_{OL}	13	14				8	1,16
Threshold Voltage	Logic 1	V_{OHA}	13 13			2 15		8 8	1,16 1,16
Threshold Voltage	Logic 0	V_{OLA}	13			14		8	1,16
Switching Times	(50Ω Load)					**Pulse In**	**Pulse Out**	**–3.2 V**	**+2.0 V**
Propagation Delay		t_{14+13-} t_{14-13+}	13 13			14 14	13 13	8 8	1,16 1,16
Rise Time	(20 to 80%)	t_{13+}	13			14	13	8	1,16
Fall Time	(20 to 80%)	t_{13-}	13			14	13	8	1,16

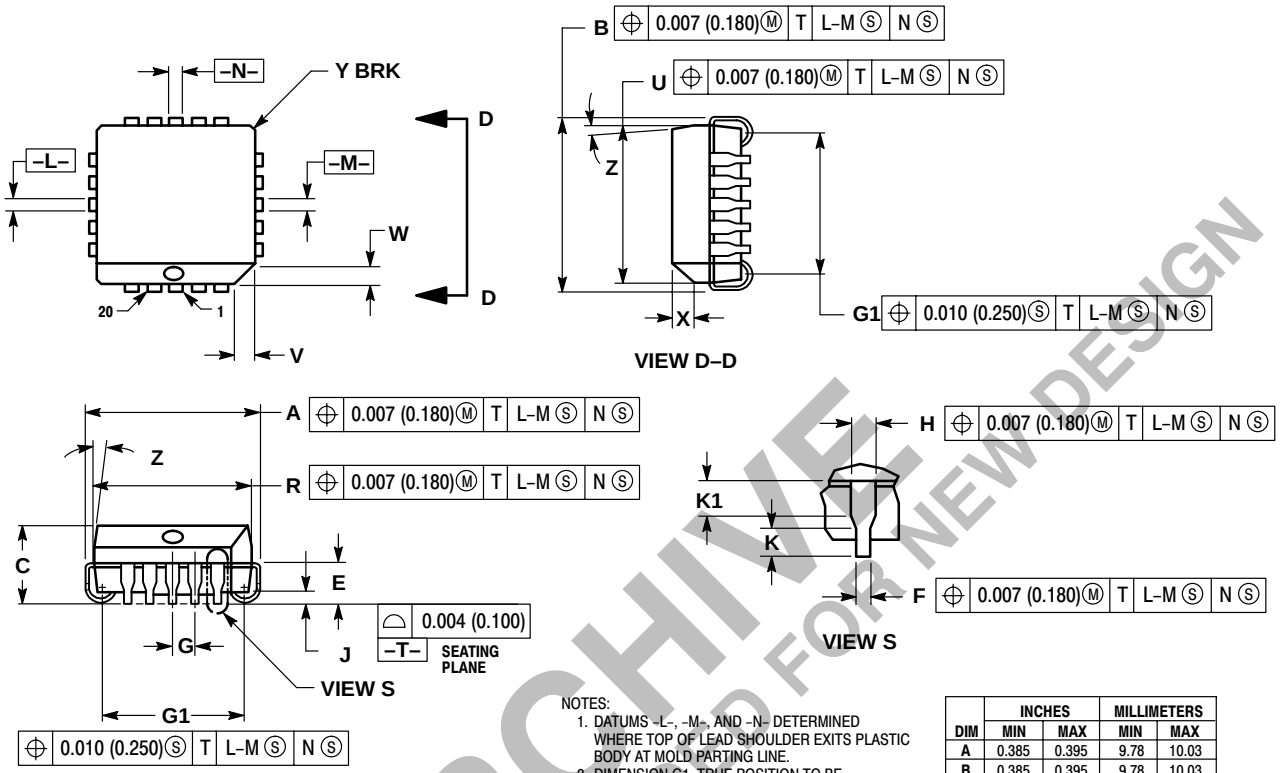
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

FIGURE 1 — HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



PACKAGE DIMENSIONS

PLCC–20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775–02
ISSUE C

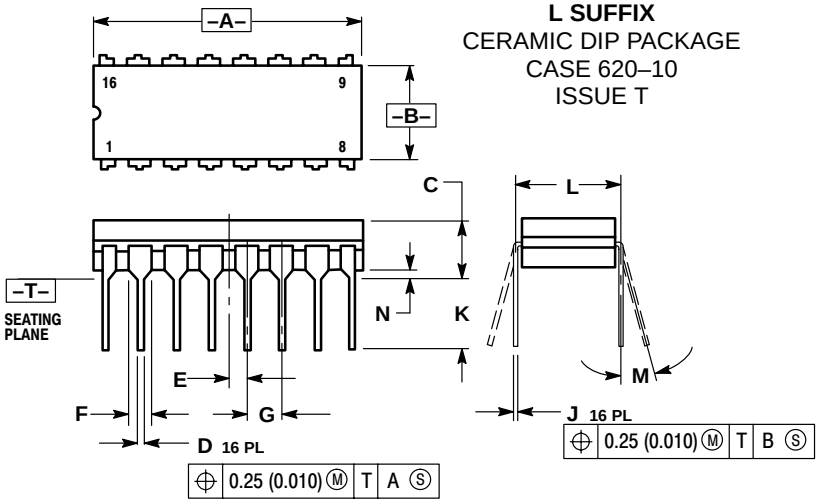


NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

PACKAGE DIMENSIONS

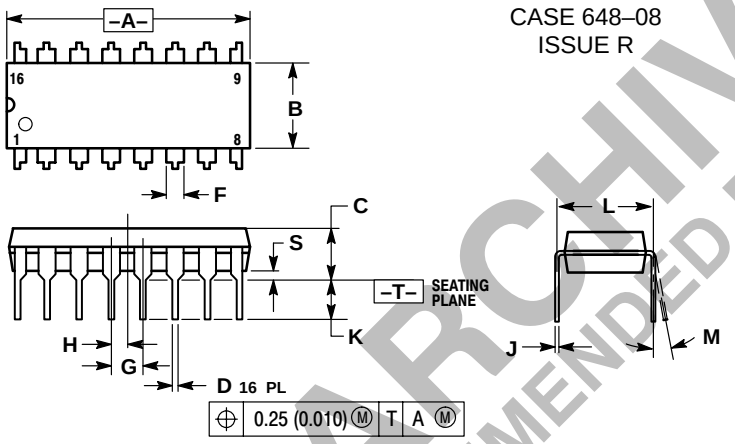
CDIP–16
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

PDIP–16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

Notes

Notes

PUBLICATION ORDERING INFORMATION

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